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3 Characteristic

Forward current		If	30			mA
Reverse voltage		Vr	5			V
Power dissipation		Pd	110			mW
Operating temperature range		Top	-25~+80			°C
Storage temperature range		Tstg	-30~+80			°C
Peak pulsing current 1/8 duty f=1KHz		Ifp	125			mA
Wavelength atpeak emission	If=20mA	peak	620	630	635	nm
Spectral half bandwidth	If=20mA			10		
Forward voltage	If=20mA	Vf	1.8	2.0	2.4	V
Luminous intensity	If=20mA	Iv	1300	1650	2000	mcd



Viewing angle at 50% IV	If=10mA		--	120	--	Deg
Reverse current	Vr=5V	Ir	--	--	5	μA
Useful life	-	IF=20mA	100000			H

Typical Electrical/Optical Characteristics Curves
(Ta=25° Unless Otherwise Noted)

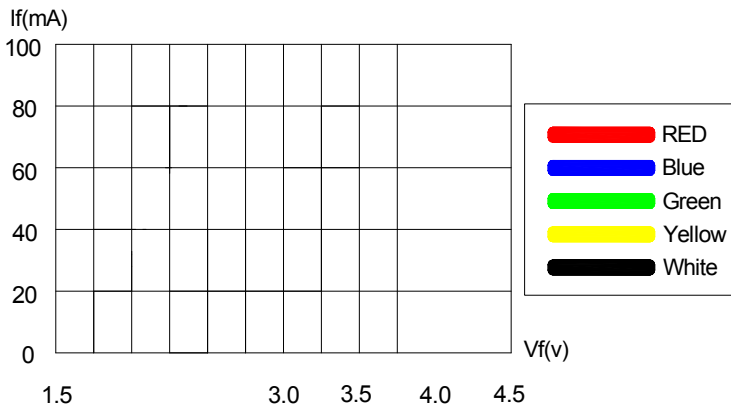


Fig.1 Forward Current vs Forward Voltage)

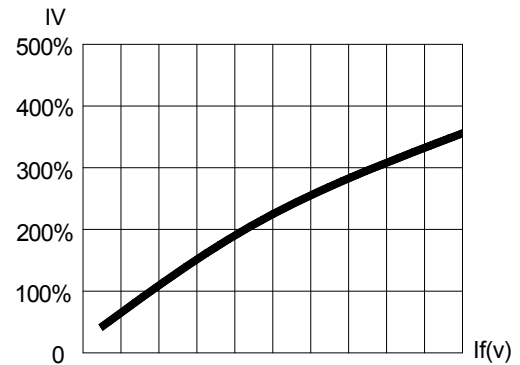


Fig.2 Relative Luminous Intensity vs Forward Voltage

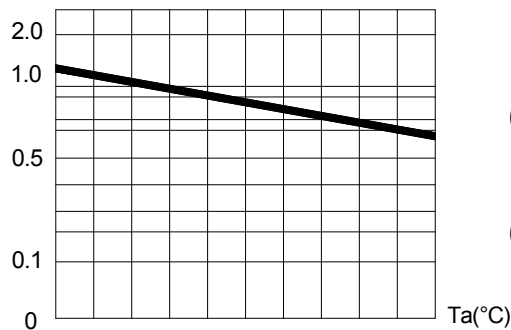


Fig.3 Relative Luminous Intensity vs Ambient Temperature

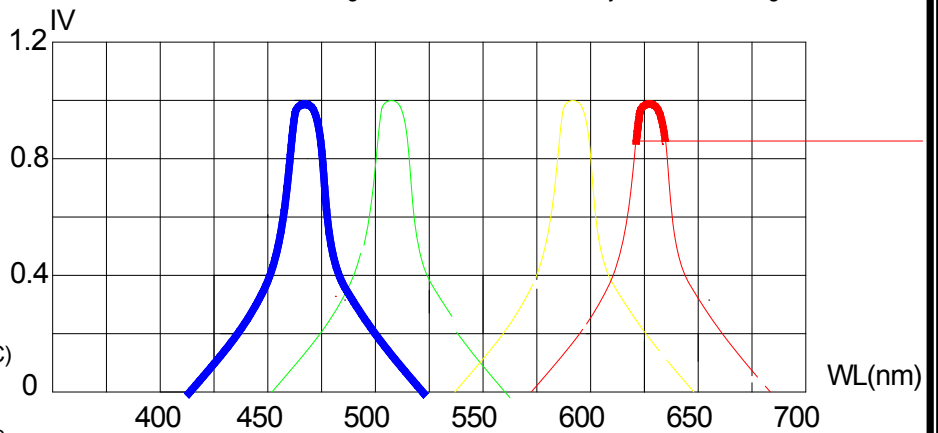


Fig.4 Relative Luminous Intensity vs Wavelength

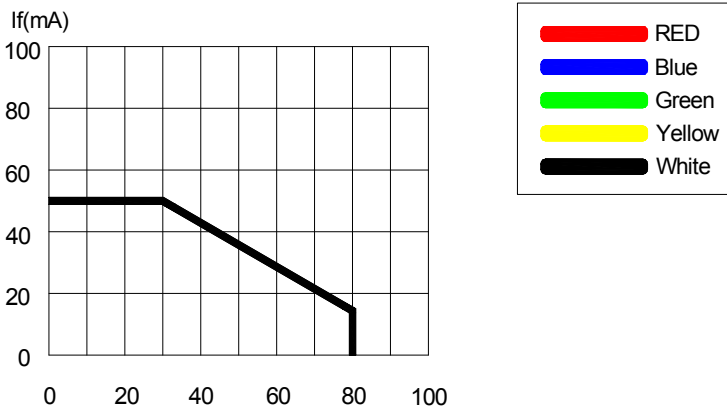
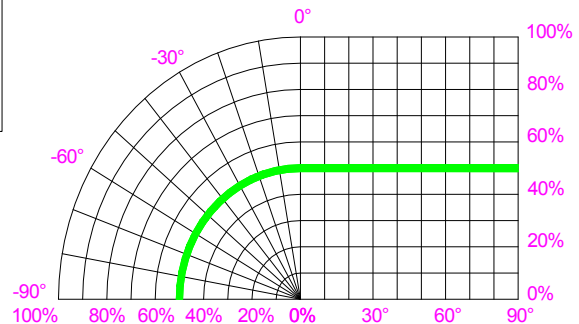


Fig.5 Maximum Forward Current vs Ambient Temperature

Directive Characteristics





1	Tin-plated test	Temp 260 ±5	5 secd.	76 PCS	0/1
2	Back & forth test under high & low temp at intervals	High temp. +85 30min to 5min to -55 30min	50 bout	76 PCS	0/1
3	Heat pounding test	High emp. +100 30min To 10sec to -10 30min	50 bout	76 PCS	0/1
4	High storage temp.	Temperature 100	1000 Hr.	76 PCS	0/1
5	Low storage temp.	-55	1000 Hr.	76 PCS	0/1
6	Life span test	VF=1.9V IF=20mA	1000 Hr.	76 PCS	0/1
7	Test under high temp.& high Humidity	85 /85%RH	1000 Hr.	76 PCS	0/1

i Iron Soldering: the Iron (max 30W) end temperature less than 300 , soldering time≤3 seconds, soldering position is minim 2mm from body.

ii Dip Soldering: Max temperature is 260 , time ≤5, the position is minim 2mm from body.

i Bracket must be bent only if 2mm from colloid.

ii Bracket mould must be finished by fixture or professionals.

iii Bracket mould must be finished before soldering.

iv Bracket mould should assure the consistent between the pin, the distance gap of leads and the circuit board.

i. It should be pay attention to the ordering of all the devices in case of wrong polarity. Devices can't be too close to the heat components, working conditions can't surpass the limits.

ii. It should not assemble LED when the leads are deformed.

iii. When decide to assemble in holes, accurately account the sizes of holes and holes distance of the line base

iv. Suggest using guard sheath positioning

v. It should avoid any kinds of quake or force on LED, before the soldering temperature returns normal.

It should be very cautious. When clean the body with chemicals. Some chemicals may bring damages to the surface, and bring color fading, such as, Trichloroethylene, Acetone. Should use ethanol to wipe, dip for no more than 3 minutes under the normal temperature

